SL-SMT 5.08HC/03/270GL 3.2AU BK BX

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

Product image

High-temperature-resistant, straight, open pin header. Packed in box or tape. On tape and with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 5.08 mm, Number of poles: 3, 270°, Solder pin length (l): 3.2 mm, Gold-plated, black, Box
Order No.	1446350000
Type	SL-SMT 5.08HC/03/270GL 3.2AU BK BX
GTIN (EAN)	4050118251524
Qty.	100 pc(s).
Product data	IEC: / 27.5 A UL: / 18.5 A
Packaging	Box

Creation date March 23, 2021 11:13:06 PM CET

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Technical data

Dimensions and weights

Depth	12 mm	Depth (inches)	0.472 inch
Height	11.7 mm	Height (inches)	0.461 inch
Height of lowest version	8.5 mm	Net weight	1.713 g
Width	18.44 mm	Width (inches)	0.726 inch

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 inch	Outgoing elbow	270°
Number of poles	3	Solder pin length (l)	3.2 mm
Solder pin length tolerance	0 / -0.3 mm	Solder pin dimensions	d = 1.2 mm, Octagonal
L1 in mm	10.16 mm	L1 in inches	0.4 inch
Number of rows	1	Pin series quantity	1
Volume resistance	≤5 mΩ	Plugging force/pole, max.	9 N
Pulling force/pole, max.	7 N		

Material data

Colour	black	Colour chart (similar)	RAL 9011
Insulating material group	IIIa	Comparative Tracking Index (CTI)	≥ 175
Contact material	CuMg	Contact surface	Gold-plated
Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt	Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn / 1.7...2.3 µm Au
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	100 °C
Temperature range, installation, min.	-30 °C	Temperature range, installation, max.	100 °C

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A		

Rated data acc. to CSA

Rated current (Use group B / CSA)	18.5 A	Rated current (Use group D / CSA)	18.5 A

Rated data acc. to UL 1059

Institute (UR)		Certificate No. (UR)	E60693
Rated current (Use group B / UL 1059)	18.5 A	Reference to approval values	Specifications are maximum values, details - see approval certificate.

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Technical data

Packing

Packaging	Box	VPE length	60 mm
VPE width	102 mm	VPE height	115 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals	
ROHS	Conform
UL File Number Search	E60693

Downloads

Engineering Data	STEP

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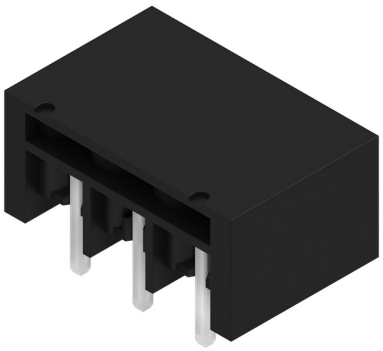
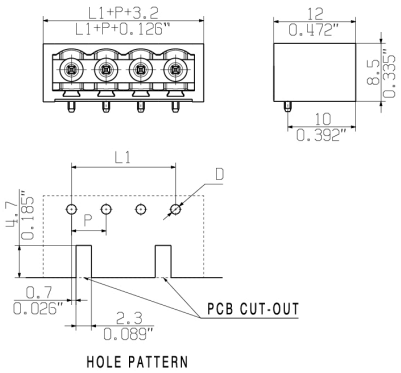
Drawings

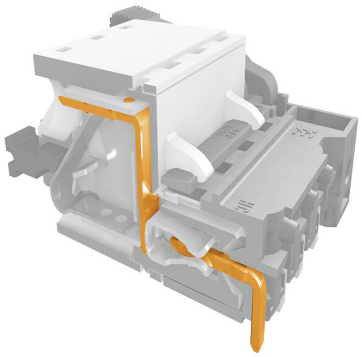
Product image



Dimensional drawing



Product benefits



Safe power transmission
Proven properties

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Wave Solder Profile

Recommended wave solderding profiles

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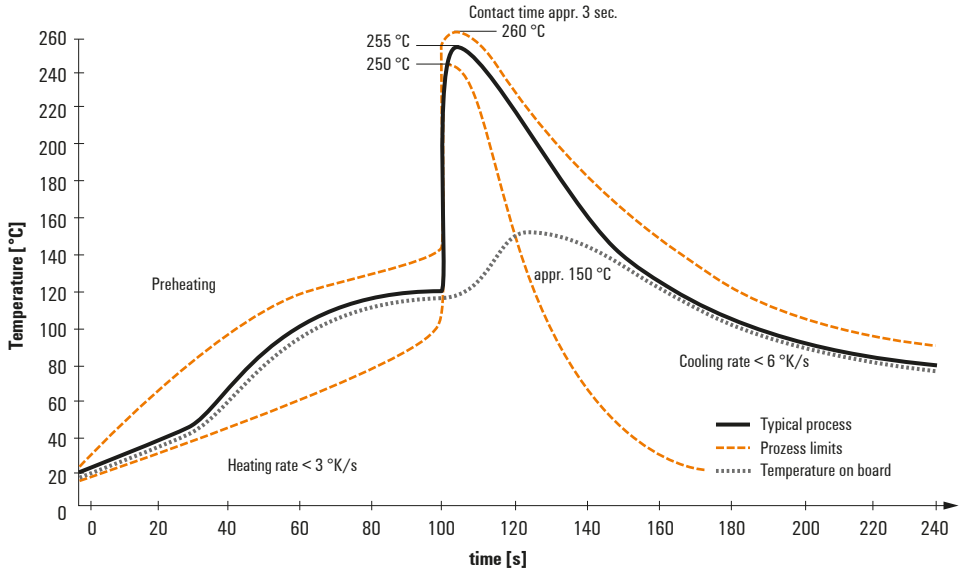
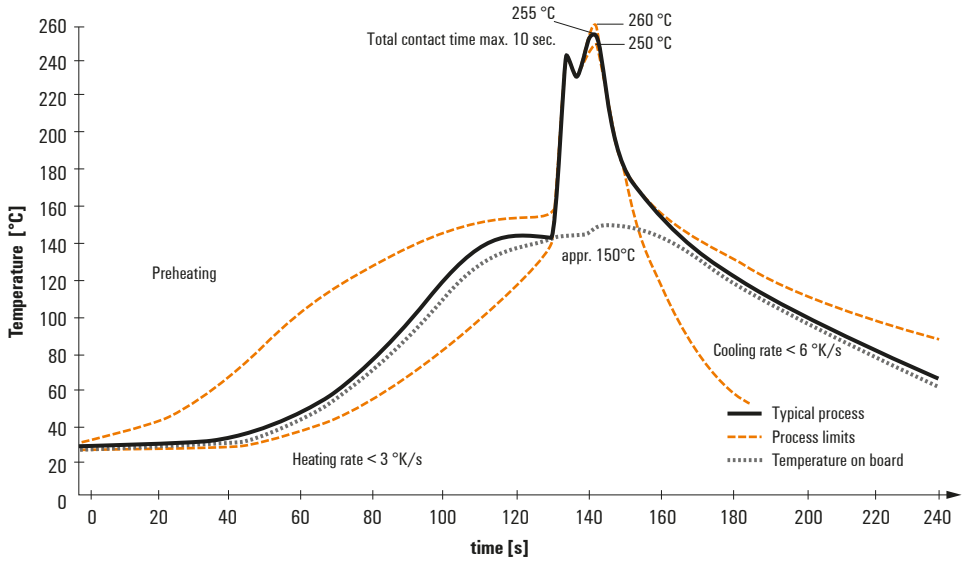
Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Reflow Solder Profile

Recommended reflow soldering profile

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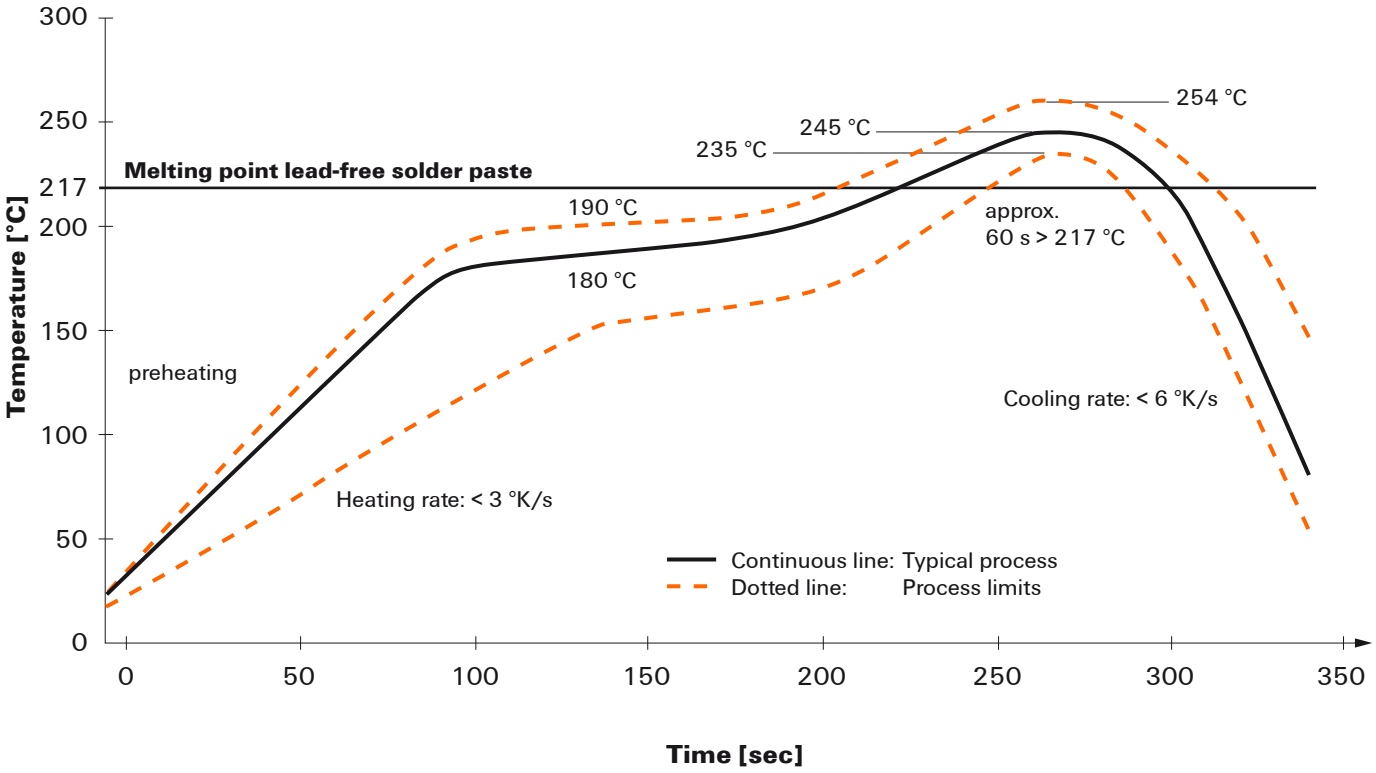

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.